

IN THE SPECIFICATION

Please amend the specification at paragraph [0032] as follows:

The method 211 may include attaching a composition that includes about 85%-98% by weight of lead, about 1%-12% by weight of silver, and the ~~the~~ balance of tin as a second lead finish to the surface of the component lead at block 225. Some embodiments may comprise attaching a composition that includes about 0%-4% by weight of silver. Some embodiments may include attaching a composition that comprises about 80%-98% by weight of lead, about 0%-4% by weight of silver, and tin, including the balance of tin. Attaching the composition may include attaching the composition using a plating process at block 229. Alternatively, or in addition, attaching the composition may further include attaching the composition using a coating process at block 231. The method 211 may conclude with attaching the component lead to an electronic component at block 235 if the lead does not already form an integral part of a package structure, for example.